/ Descriptions

TO-277

TO-277 Plastic package Schottky diode .

/ Features

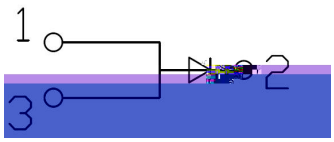
V_F(typ)=0.21V

High Forward Surge Capability, Ultra Low Forward Voltage Drop V_F(typ)=0.21V, Excellent High Temperature Stability. HF Product.

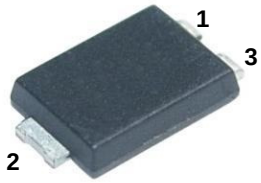
/ Applications

For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications.

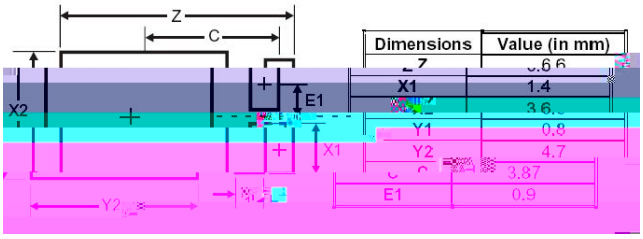
/ Equivalent Circuit



/ Pinning



PIN1 Anode PIN 2 Cathode PIN 3 Anode



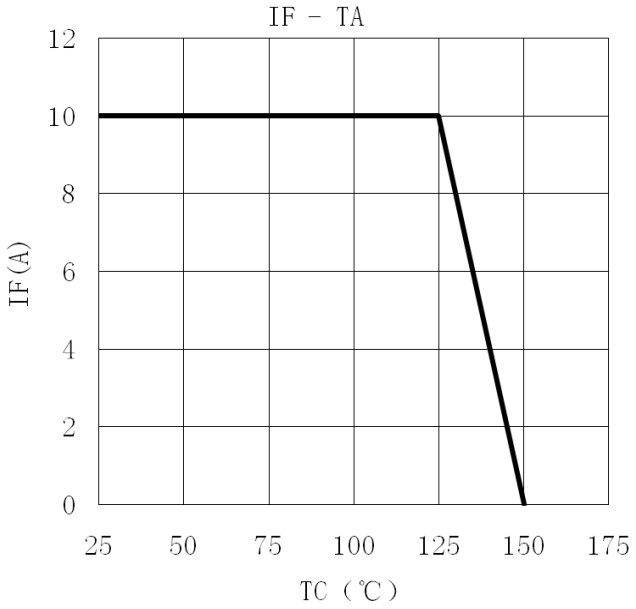
Suggested Pad layout

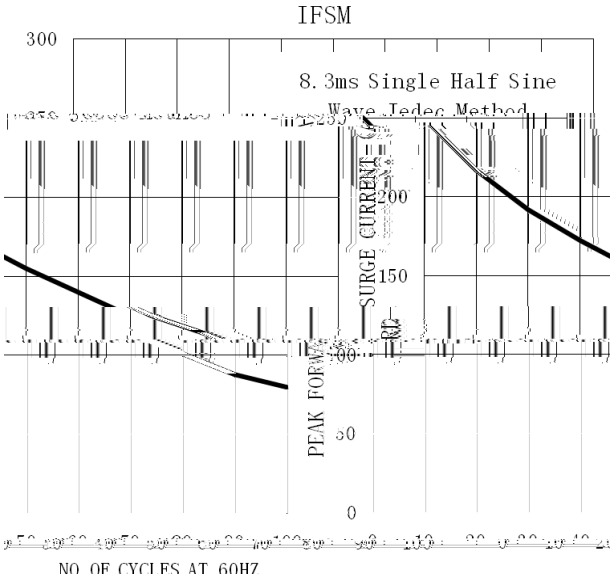
/ h_{FE} Classifications & Marking

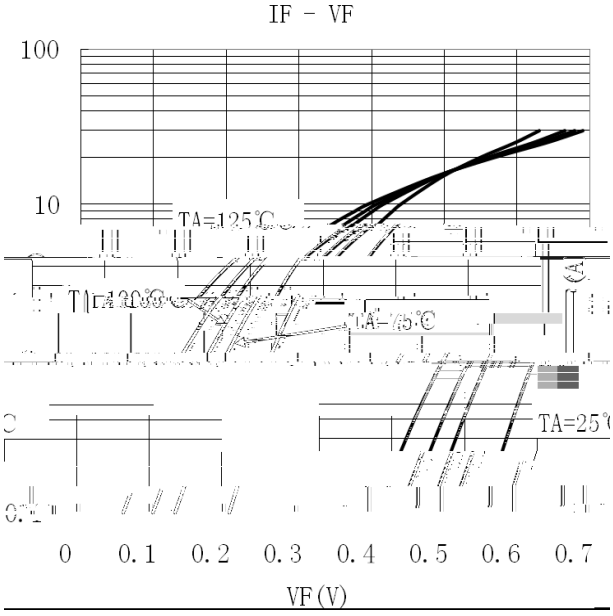
See Marking Instructions.

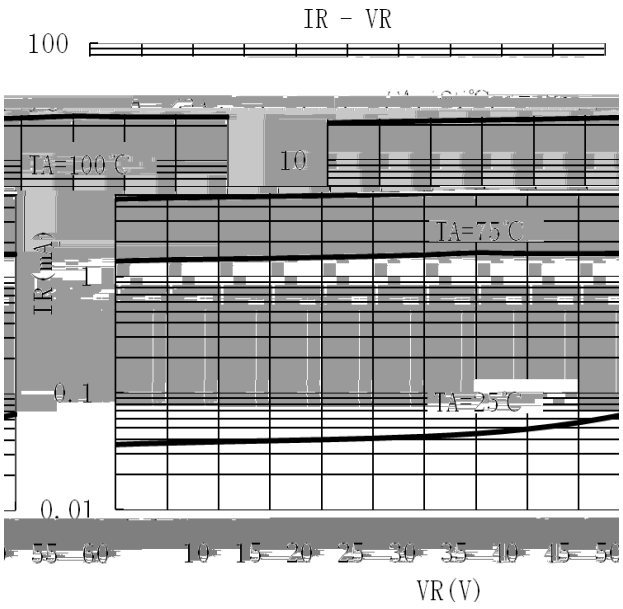
Parameter	Symbol	Rating	Unit

/ Electrical Characteristic Curve

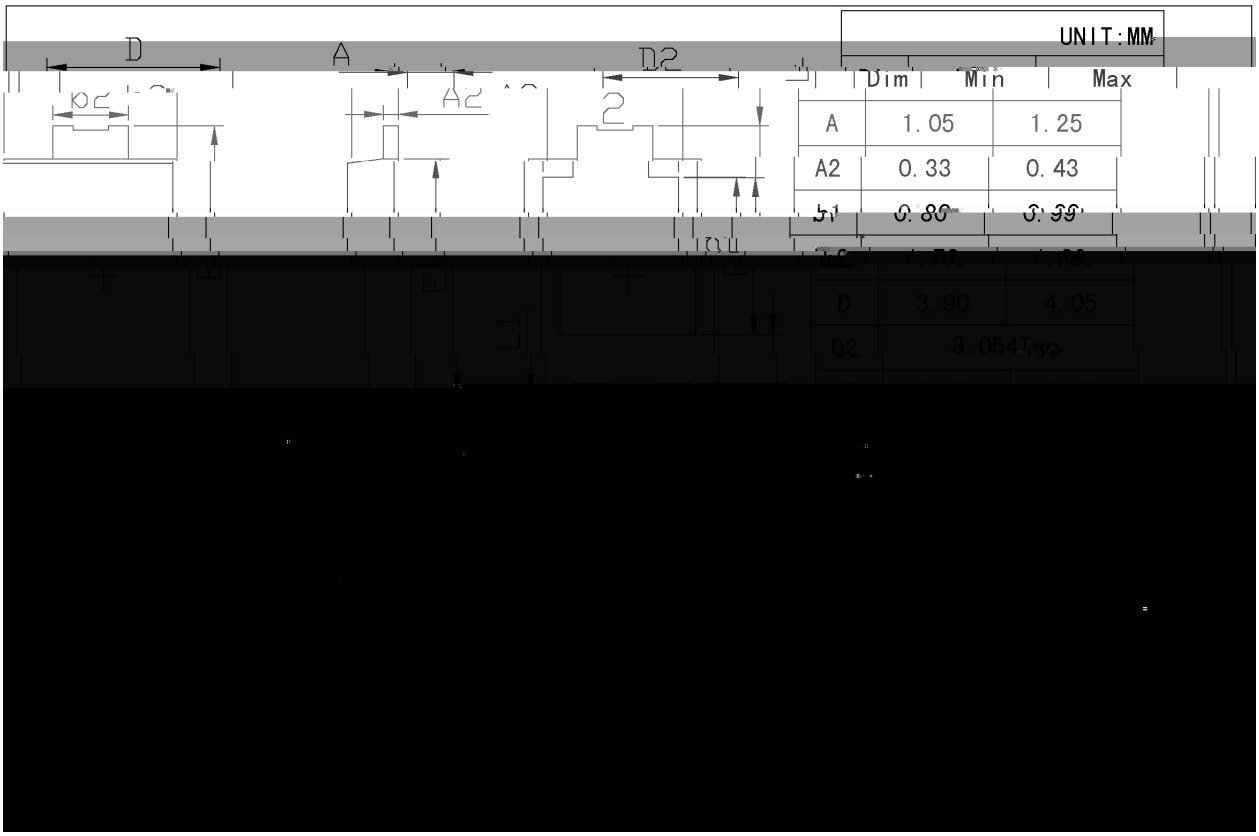




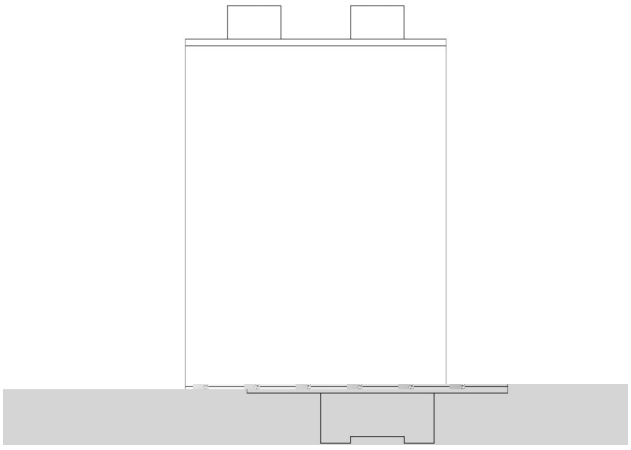




/ Package Dimensions

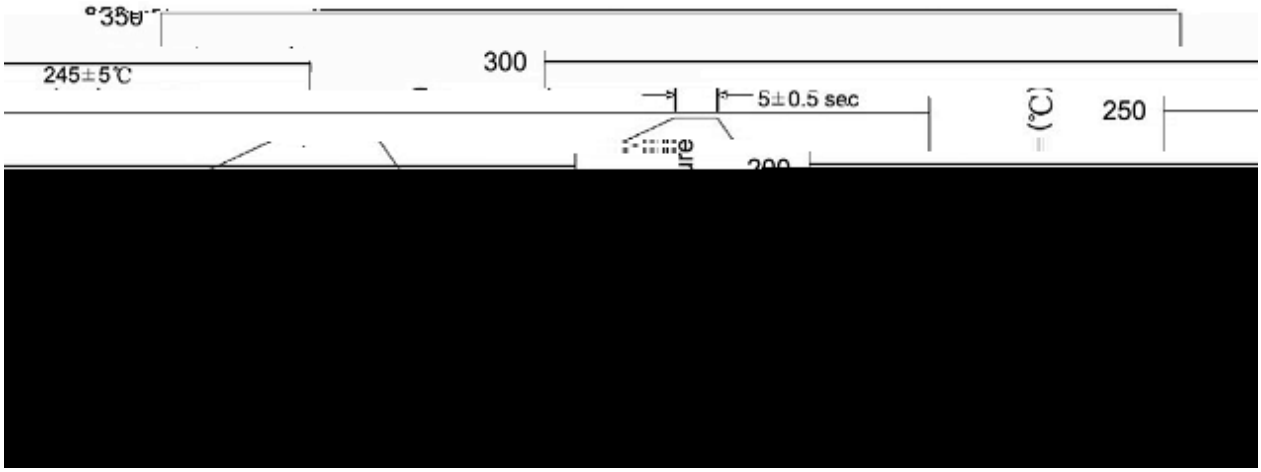


/ Marking Instructions



10S60

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



1	150	180		60	90sec;	Note:	
2	245±5				5±0.5sec;	1.Preheating:150~180	, Time:60~90sec.
3			2	10	/sec.	2.Peak Temp.:245±5	, Duration:5±0.5sec.
						3. Cooling Speed: 2~10	/sec.

/ Resistance to Soldering Heat Test Conditions

260±5	10±1 sec.	Temp.:260±5	Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension		(unit mm^3)
	Units/Reel /	Reels/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Reel	Inner Box	Outer Box
TO-277	5,000	3	15,000	6	90,000	13 ×12	360×360×50	380×335×366

/ Notices